

Fraunhofer Institute for Photonic  
Microsystems IPMS

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Fraunhofer IPMS, Dresden, Germany

A new semi-transparent OLED-on-Silicon microdisplay technology enabling new optical design opportunities for slim near-to-eye optics

# Outline

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## Introduction Microdisplays @Fraunhofer IPMS

### Motivation

### Technology

- OLED-on-Silicon technology
- OLED-on-SOI transparency technology

### Results

- Optical design aspects
- Waferlevel results
- NTE module

### Conclusion

# About

Dr. Uwe Vogel  
Division Director Microdisplays & Sensors

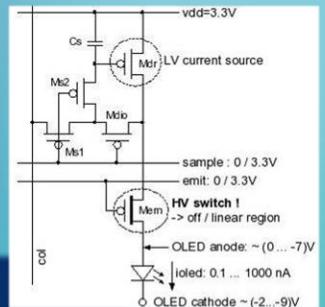


## Location: Dresden/Germany („Silicon Saxony“)

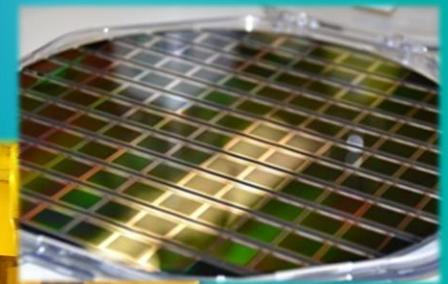


## Core competences

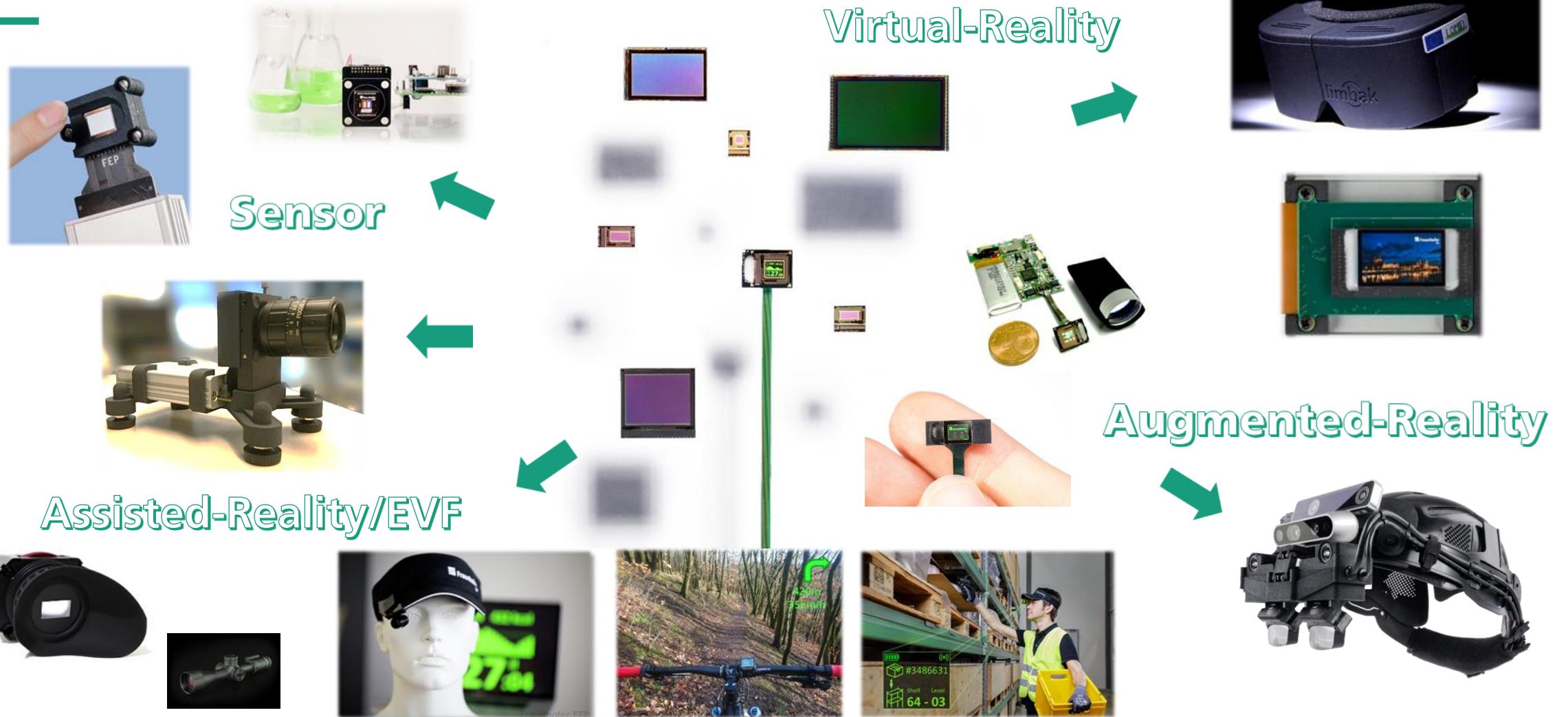
### IC design (backplane)



### Organic electronics (frontplane)



# Where do we come from? Our Background - Organic-on-Silicon



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# Motivation – AR Glasses

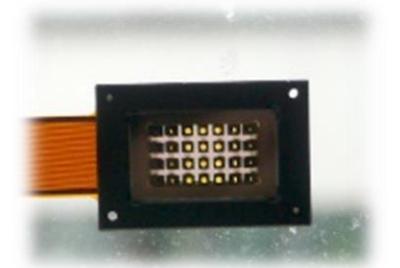
## Key Targets for AR-Glasses

- Transparency, FOV, Slim Formfactor, Low Power



## Various AR-Concepts has been presented over the last years

- **Combiner** based: Google Glass and similar
  - Beam splitter, bird bath, free-form prism...
  - **Optically efficient** but **not slim**
- **Waveguide** based: Magic Leap and similar
  - Waveguide requires high luminance – high power light engine
  - **Slim** but **not efficient**
- **Video see through**: Apple Vision Pro
  - **Nether slim nor efficient**
- New Concept: **Semi-Transparent OLED-microdisplay**
  - **Optically efficient AND slim**



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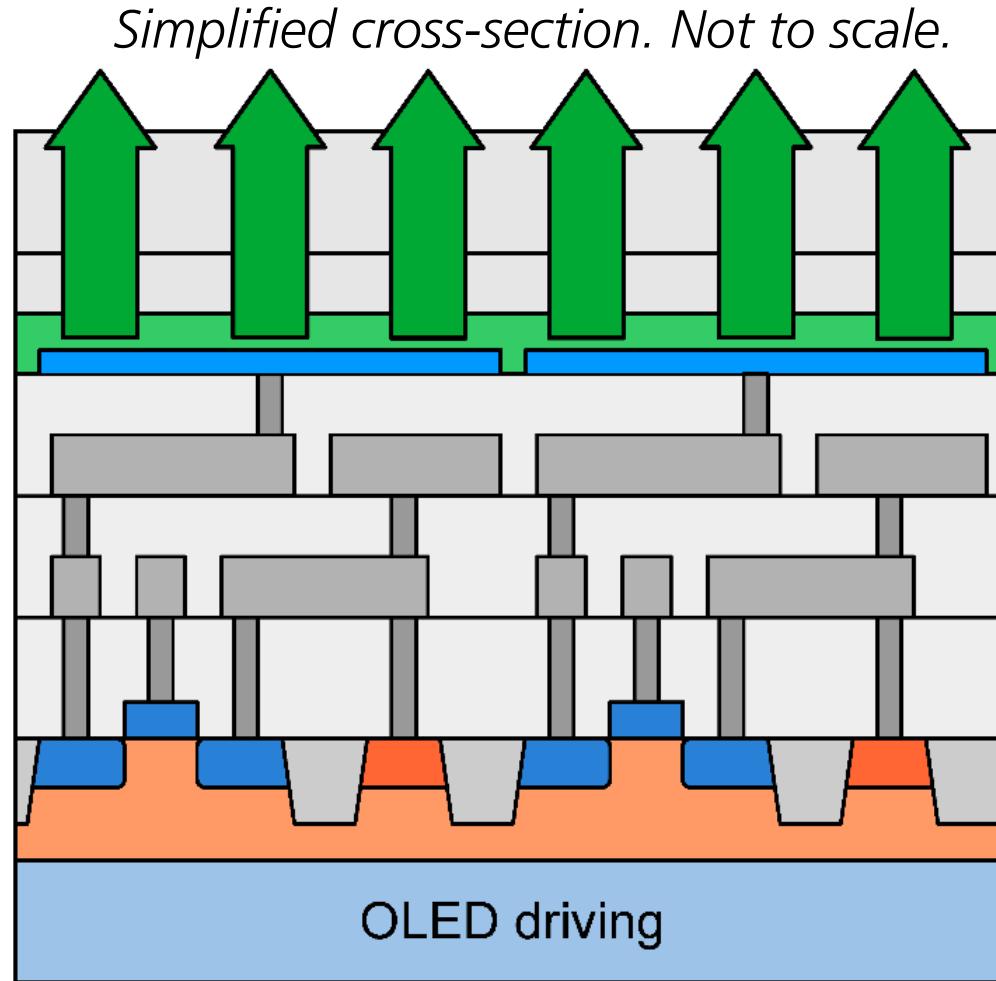
# The Base Technology: OLED-on-Silicon

## Organic-Frontplane

- Monolithic integration of organic stacks on silicon
- **OLED** for light emission

## Silicon-Backplane

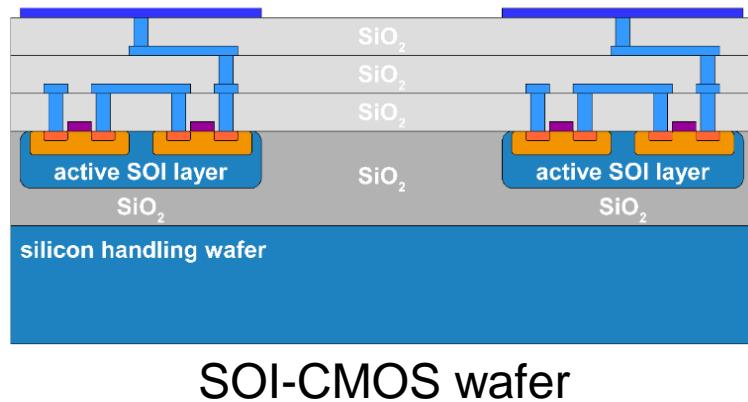
- State-of-the-art microelectronics
- Small pixel size typ.  $<10\ \mu\text{m}$
- High resolution, e.g. WUXGA (HD+)
- Integration of sensors, driving electronics, processing...



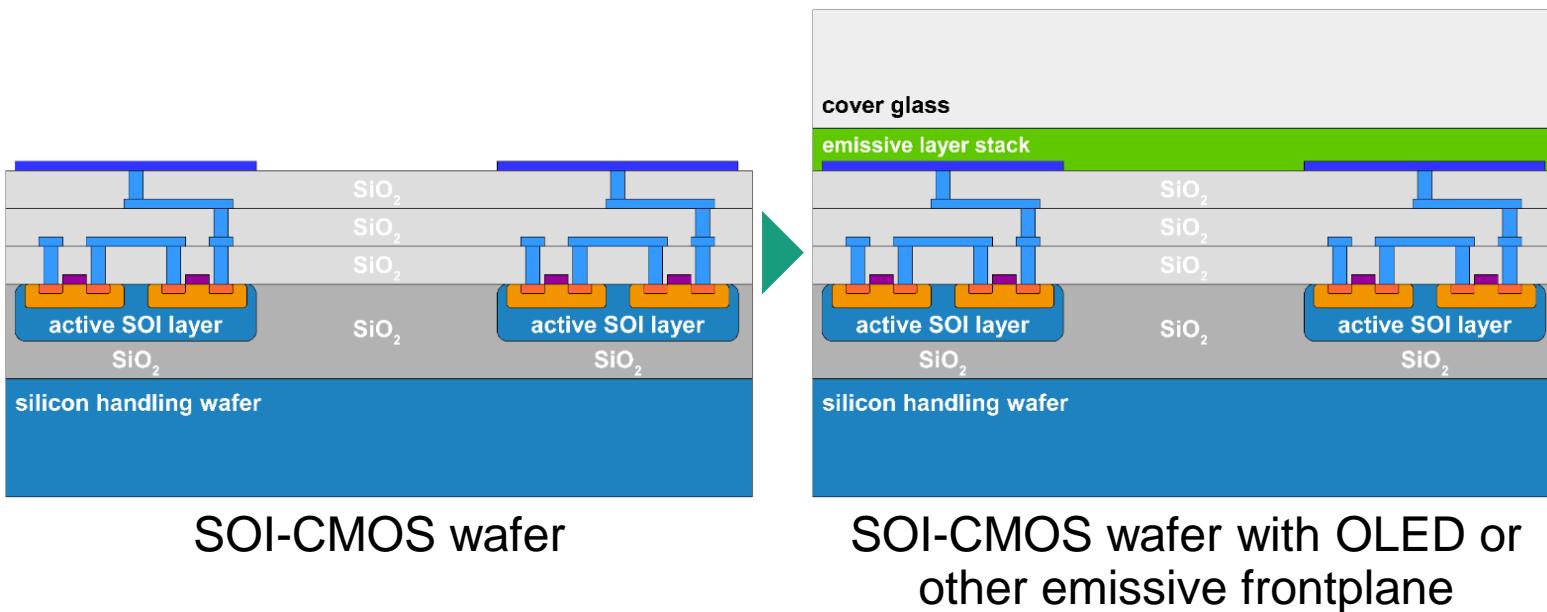
# OLED-on-SOI Transparency Technology

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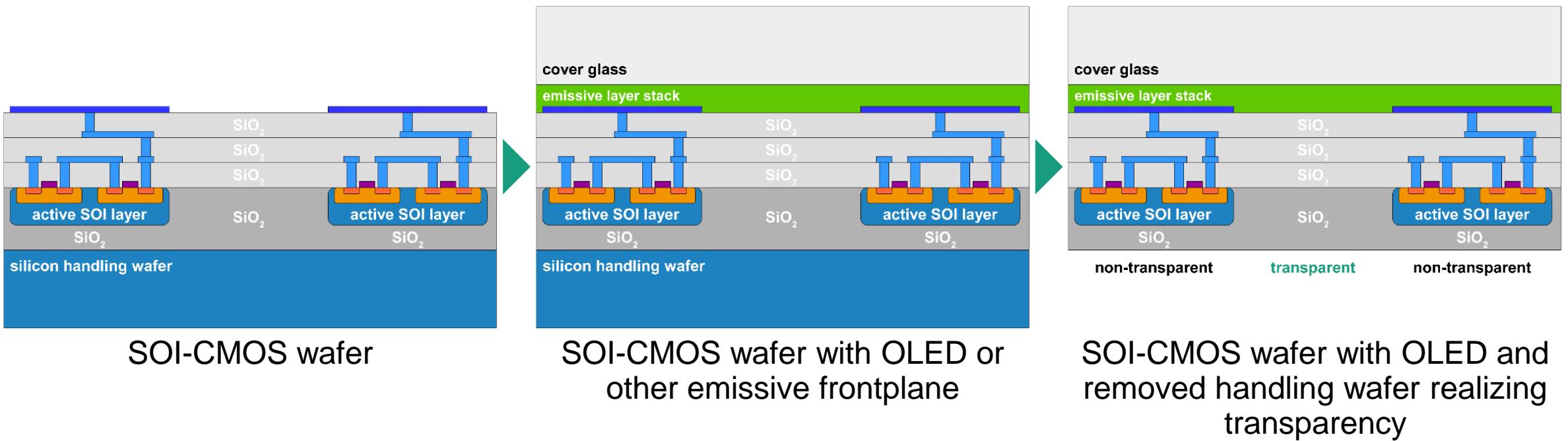
How to make silicon semi-transparent...



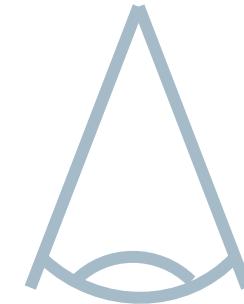
# OLED-on-SOI Transparency Technology



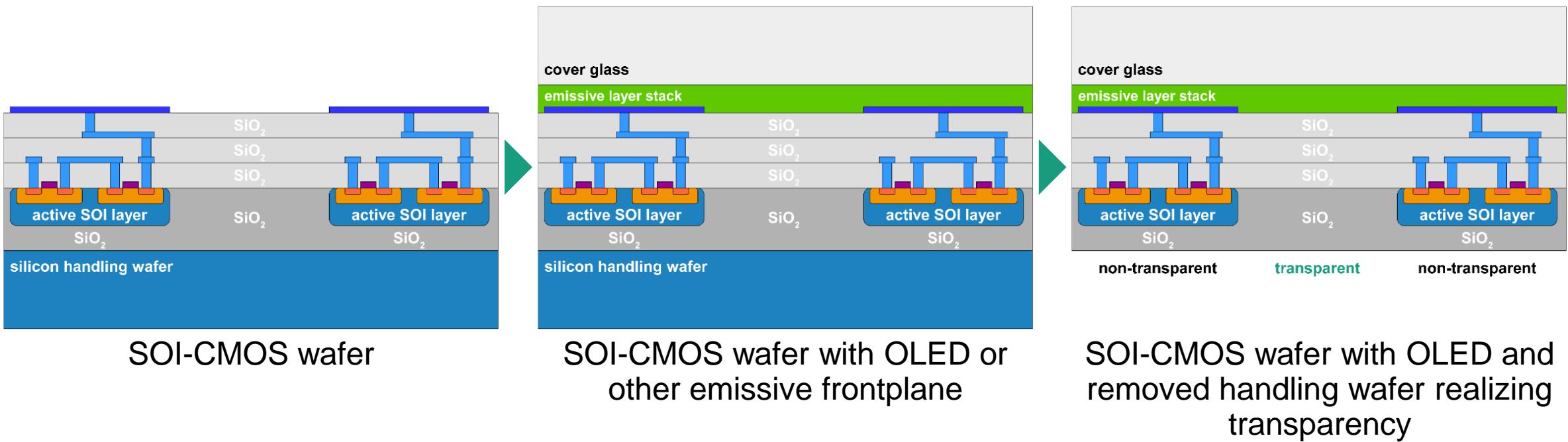
# OLED-on-SOI Transparency Technology



# OLED-on-SOI Transparency Technology



Orientation  
in near to  
eye optics



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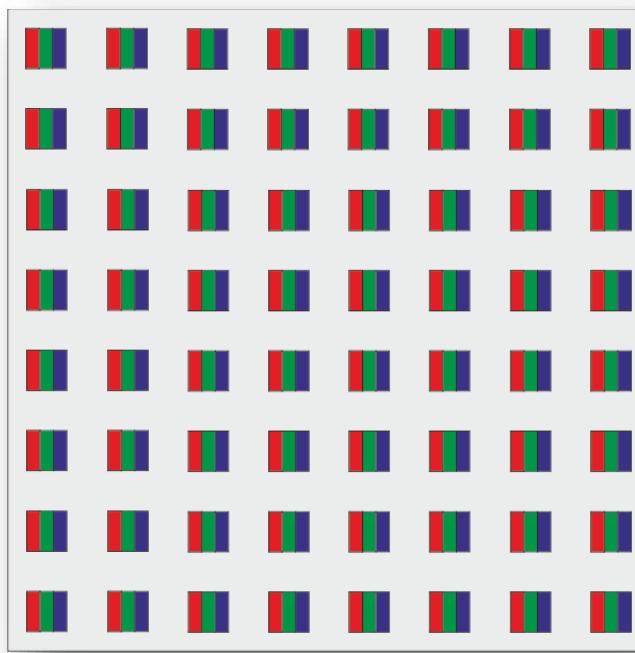
- OLED-on-Silicon technology
- OLED-on-SOI transparency technology

## Results

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- NTE module

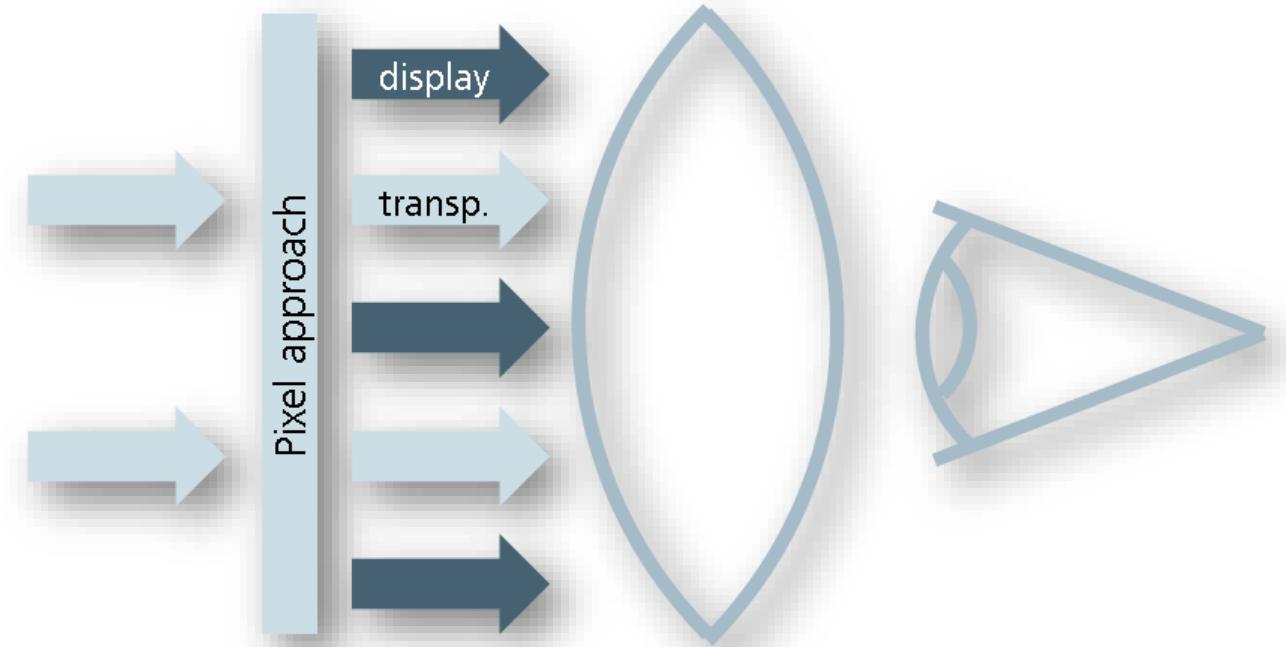
## Conclusion

# Example Optical Setup – Pixel approach



## Sparse pixels

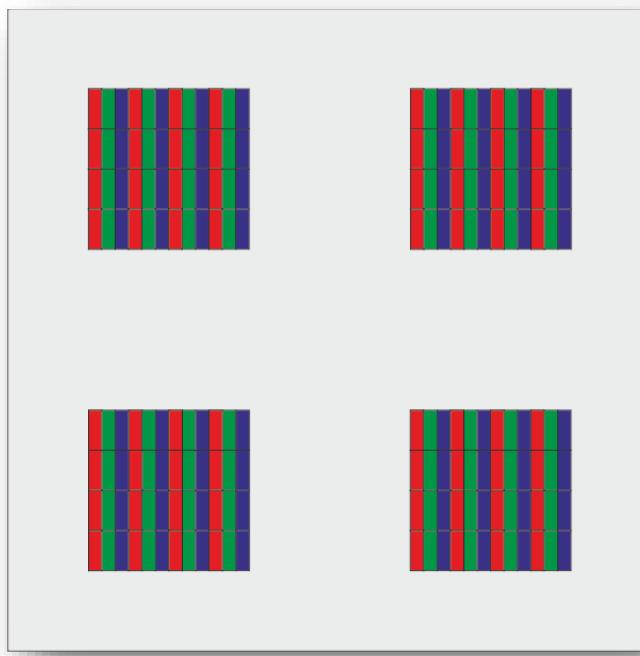
- Transparent areas  
in each pixel



## Optics

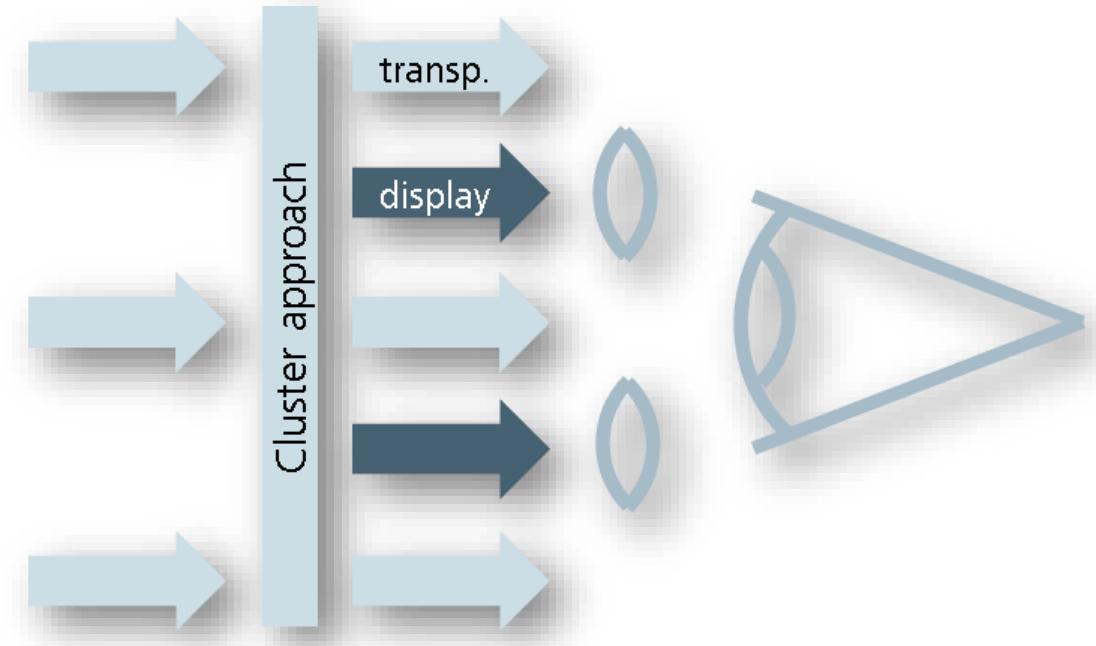
- Typically common magnification optics for display and transparent optical path

# Example Optical Setup – Cluster approach



## Sparse pixel clusters

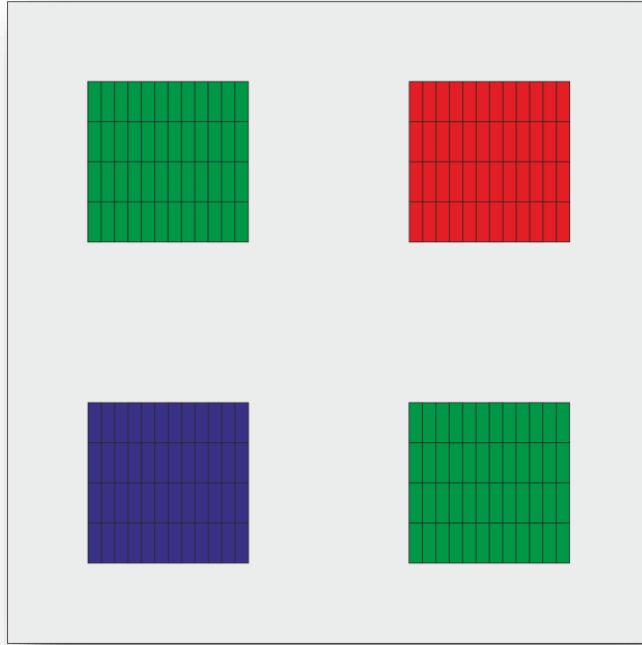
- Transparent areas between group of pixels



## Optics

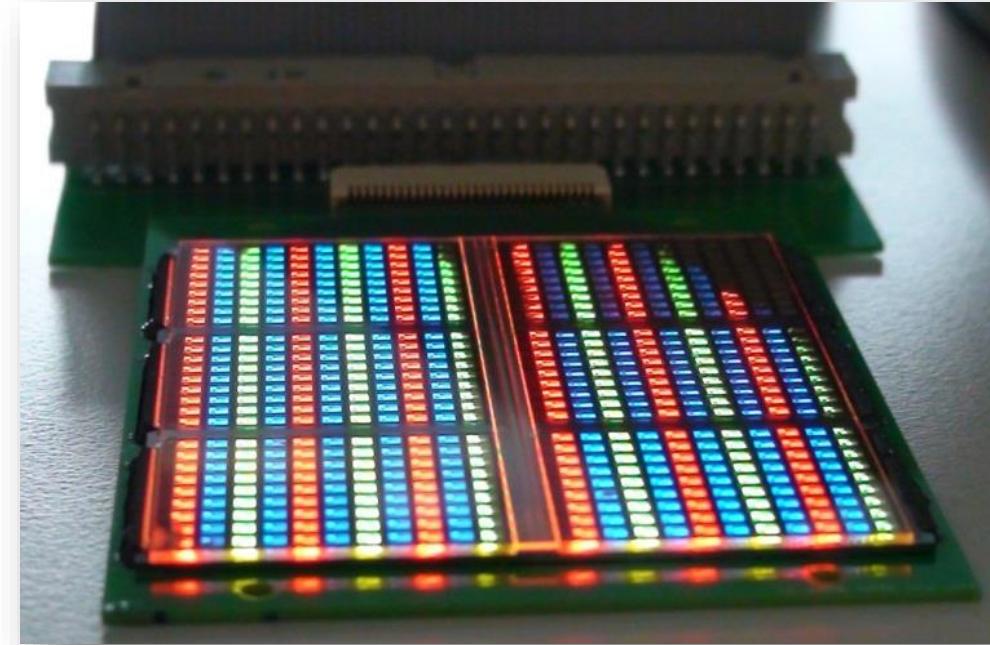
- Maintain real image path
- Magnification of display clusters

# Example Optical Setup – Cluster approach



## Sparse pixel clusters

- Monochrome emitters  
for higher power efficiency



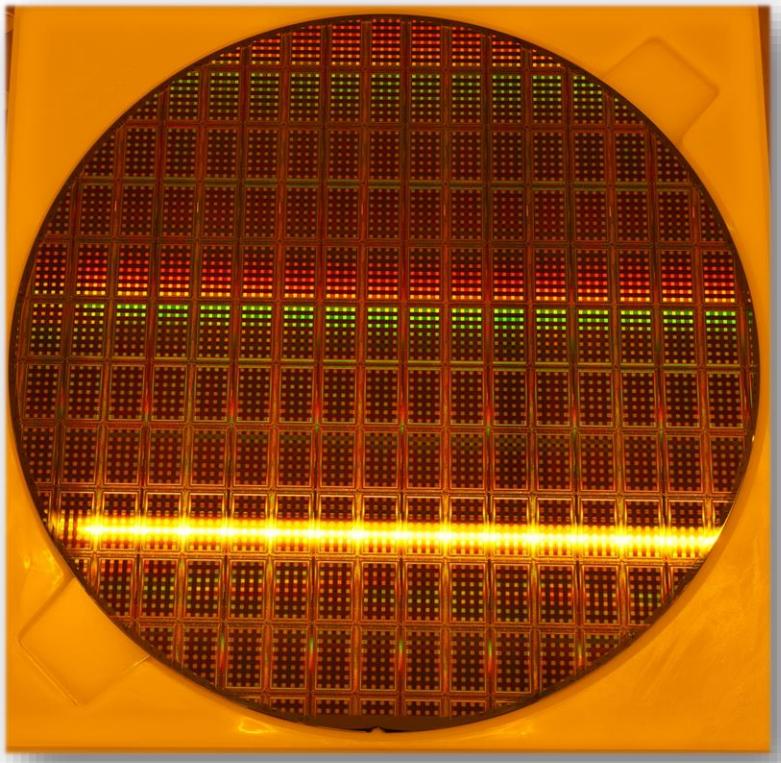
## Optics

- Combines colors of different clusters
- Good for OLED and uLED integration as color pattern is relaxed

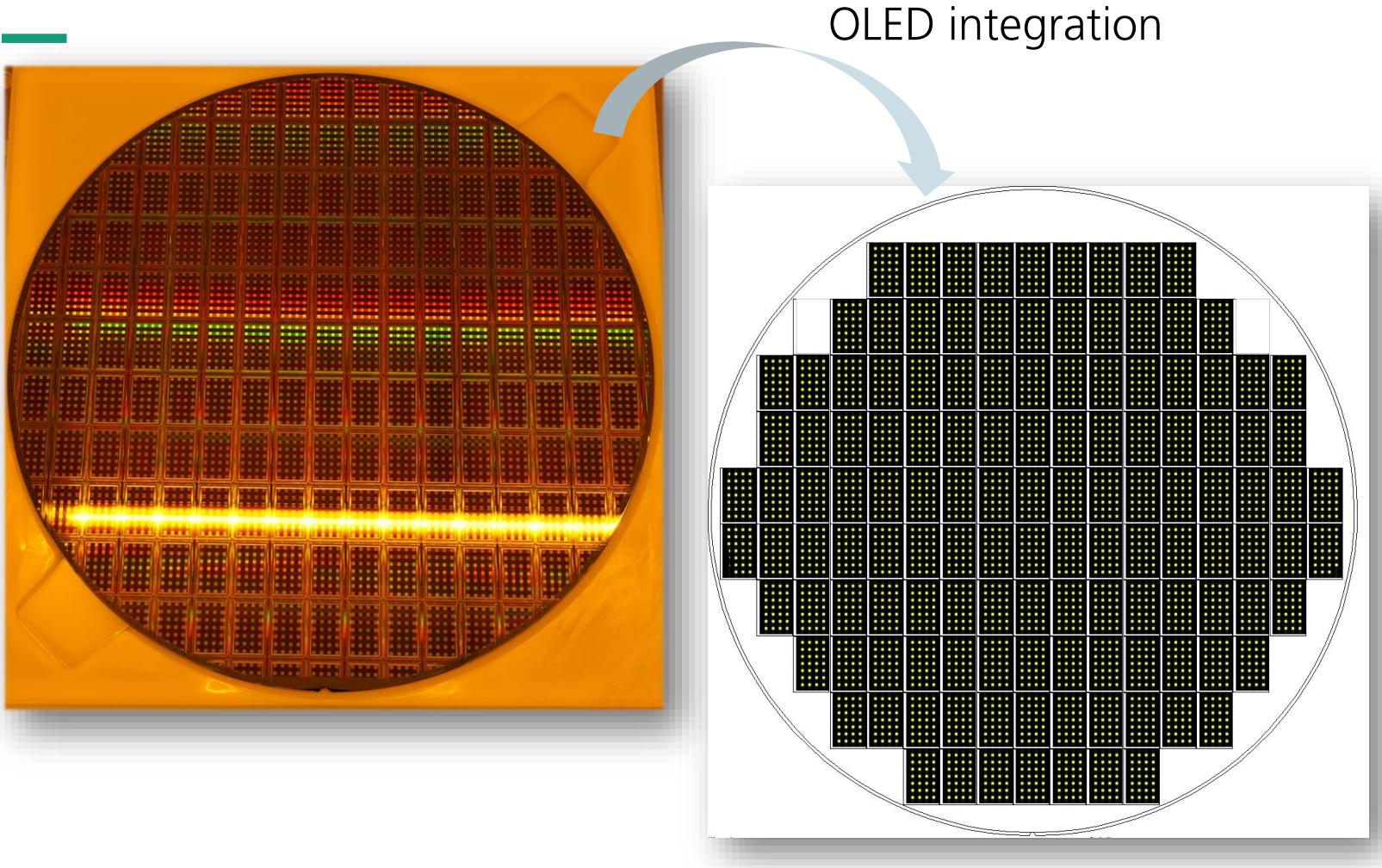
OLED, non-transparent integration  
example of colored clusters by  
Fraunhofer for projector applications  
more than 10 years ago

# Results Waferlevel Integration

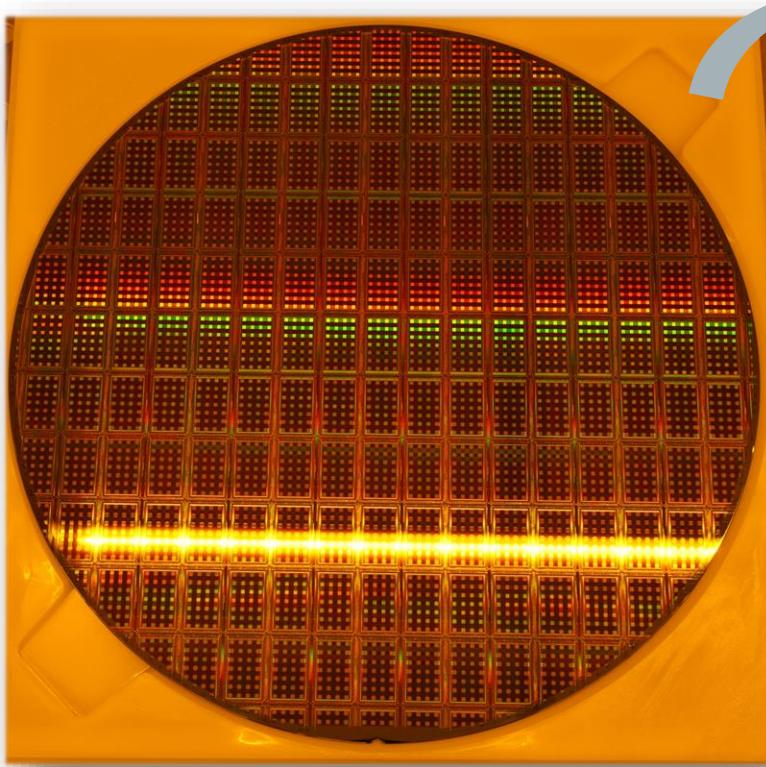
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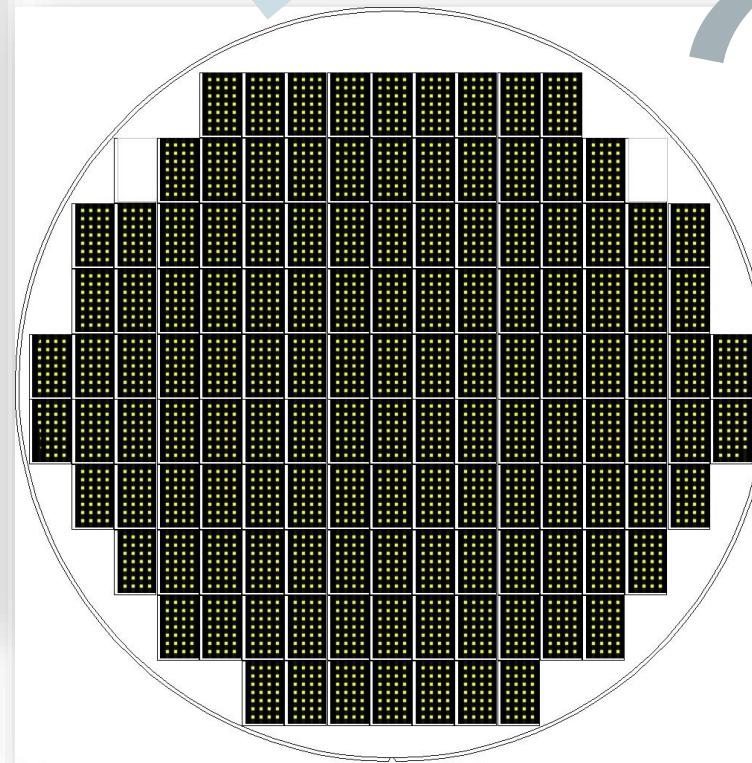
# Results Waferlevel Integration



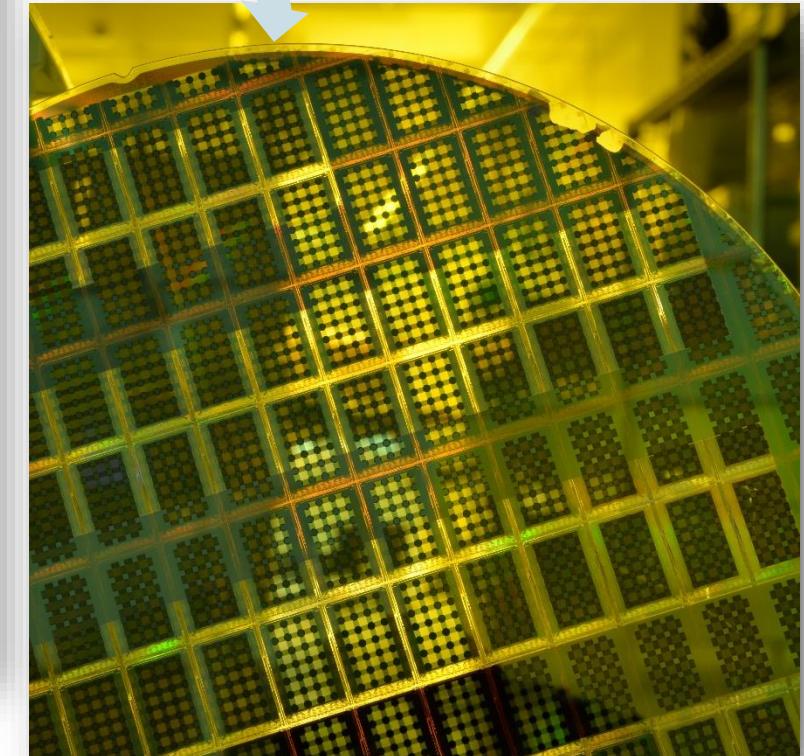
# Results Waferlevel Integration



OLED integration



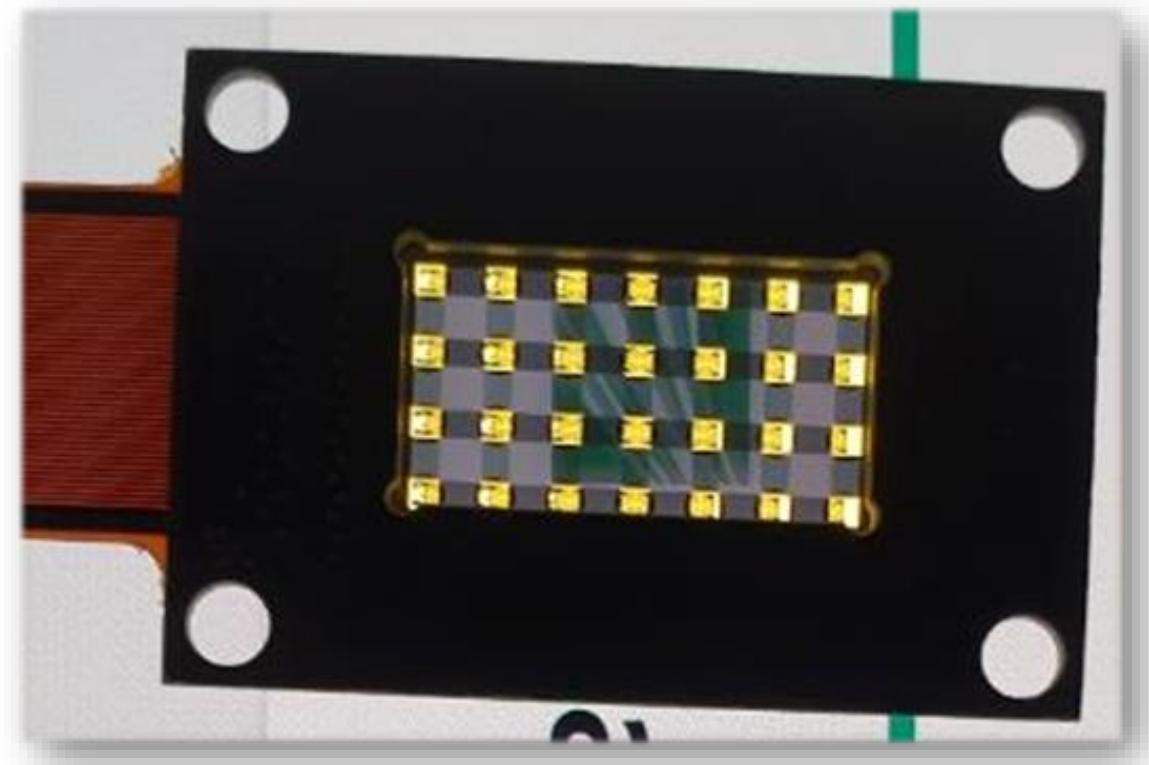
Transparency process



# Initial Samples – Without Optics

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Parameter	Value
No. of clusters	7 x 4
Cluster resolution	128 x 128 x RGBW
Cluster pitch	2240 um
Cluster size	896 um x 896 um
Sub-pixel size	3.5 um
OLED type	Common cathode
Total active area	14.3 mm x 7.6 mm



# Initial Technology Demonstrator With Optics



Microoptics supported by  **Fraunhofer**  
IOF

- Initial integration with monochrome amber white OLED stack for **luminance up to 35knits**
- Initial **transparency** of demo 22%, improved process **in lab already showed > 50% for cluster utilization of 25%** (thus providing a theoretical fill-factor based limit of 75%)



Initial AR demo with optics



Image taken through optics

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## Technical summary

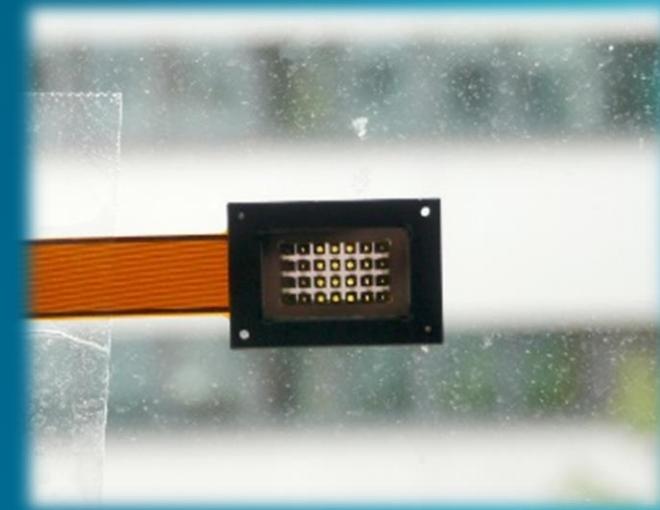
- New technology **OLED-on-SOI transparency** expands the toolbox for optical designers
- Promising **technology to solve the AR power challenge**
- Based on **production proven OLED-on-Silicon** technology – but also capable for uLED in the future
- Based on standard **wafer level** process steps
- Enables **new optical approaches** for higher optical efficiency

## IPMS Microdisplay R&D Portfolio

- Customized microdisplay developments
- Customized photonics components
- Adapted spectral emission characteristics

# Thank you!

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